

IN THE CLAIMS

The following includes the entire set of pending claims with mark-ups.

Please amend Claims 1, 6, 9 and 10.

Please cancel Claims 5 and 7.

Please add Claims 14 and 15.

1. (currently amended) A conductive contact member for establishing a temporary electric contact by being applied under a resilient force to an object to be contacted that includes solid solder, the conductive contact member comprising a compression coil spring formed of a wire with a layer of highly electrically conductive material resistant to solder deposition, wherein the layer and consisting consists of gold containing a small amount of silver, the layer being contains no palladium, and is formed at least over a conductive contact part of said ~~conducte~~ conductive contact member compression coil spring so that said conductive contact part of said ~~conducte~~ conductive contact member compression coil spring may not be contaminated by deposition of solder from said object to be contacted.
2. (original) A conductive contact member according to claim 1, wherein said layer is formed by plating.
3. (canceled)
4. (previously presented) A conductive contact member according to claim 1, wherein silver is added to gold by 0.01% to 8%.
5. (canceled)
6. (currently amended) A conductive contact member according to claim 1, wherein said conductive contact member is [[made]] comprised of steel.
7. (canceled)

8. (original) A conductive contact member according to claim 1, wherein said conductive contact member is in the form of a compression coil spring having a contact part consisting of closely wound turns of a coil wire, and said solder resistant layer is formed over an outer surface of said closely wound turns of the coil wire.
9. (currently amended) A conductive contact member of a contact probe for establishing a temporary electric contact by being applied under a resilient force to an object to be contacted that includes solid solder, the conductive contact member comprising a compression coil spring formed of a wire with a layer of highly electrically conductive material resistant to solder deposition, wherein the layer and consisting consists of an alloy of gold added with silver, the layer being contains no palladium, and is formed at least over a conductive contact part of said conductive contact member compression coil spring so that said conductive contact part of said conductive contact member compression coil spring may not be contaminated by deposition of solder from said object to be contacted.
10. (currently amended) A conductive contact member of a contact probe for establishing a temporary electric contact by being applied under a resilient force to an object to be contacted that includes solid solder, the conductive contact member comprising a compression coil spring formed of a wire with a layer of highly electrically conductive material resistant to solder deposition, wherein the layer and consisting consists of a homogeneous mixture of gold added with silver, the layer being contains no palladium, and is formed at least over a conductive contact part of said conductive contact member compression coil spring so that said conductive contact part of said conductive contact member compression coil spring may not be contaminated by deposition of solder from said object to be contacted.
11. (previously presented) A conductive contact member according to claim 1, wherein an amount of silver added to gold is between 0.01% and 5%.
12. (previously presented) A conductive contact member according to claim 9, wherein an amount of silver added to gold is between 0.01% and 5%.

13. (previously presented) A conductive contact member according to claim 10, wherein an amount of silver added to gold is between 0.01% and 5%.
14. (new) A conductive contact member of a contact probe for establishing a temporary electric contact by being applied under a resilient force to an object to be contacted that includes solid solder, the conductive contact member comprising a needle member with a layer of highly electrically conductive material resistant to solder deposition, wherein the layer consists of an alloy of gold added with silver, contains no palladium, and is formed at least over a conductive contact part of said needle member so that said conductive contact part of said needle member may not be contaminated by deposition of solder from said object to be contacted.
15. (new) A conductive contact member of a contact probe for establishing a temporary electric contact by being applied under a resilient force to an object to be contacted that includes solid solder, the conductive contact member comprising a cylindrical rod member with a layer of highly electrically conductive material resistant to solder deposition, wherein the layer consists of an alloy of gold added with silver, contains no palladium, and is formed at least over a conductive contact part of said rod member so that said conductive contact part of said rod member may not be contaminated by deposition of solder from said object to be contacted.